



General Description

The advanced SGT MOSFET technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and converter applications.

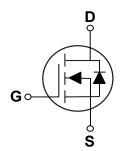
BV _{DSS}	R _{DS(ON)}	Ι _D
40 V	1.8 mΩ	195 A

Features

- $R_{DS(ON)} \le 1.8 m\Omega @V_{GS} = 10V$
- · Low Gate Charge
- · Low R_{DS(ON)}
- · Green Device Available

PPAK5X6 Pin Configuration





Applications

- · SMPS Synchronous Rectification
- DC/DC Converters

Absolute Maximum Ratings T _J =25°C unless otherwise noted							
Symbol	Parameter	Rating	Units				
V_{DS}	Drain-Source Voltage	40	V				
V_{GS}	Gate-Source Voltage	±20	٧				
I _D	Drain Current – Continuous (T _C =25°C)	195	Α				
I _{DM}	Drain Current – Pulsed (NOTE 1)	780	Α				
EAS	Single Pulse Avalanche Energy (NOTE 2)	288	mJ				
P_D	Power Dissipation (T _C =25°C)	113.6	W				
T_J	Operating Junction Temperature Range	-55 to 150	°C				
T _{STG}	Storage Temperature Range	-55 to 150	°C				
Marking Code		A4048 , ND1P8					

Thermal Characteristics					
Symbol	Parameter	Тур.	Max.	Unit	
$R_{\theta JA}$	Thermal Resistance Junction to Ambient		50	°C/W	
$R_{ heta JC}$	Thermal Resistance Junction to Case		1.1	°C/W	





Electrical Characteristics (T_{.J}=25°C, unless otherwise noted)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V_{GS} =0V , I_D =250uA	40			V
I _{DSS}	Drain-Source Leakage Current	V_{DS} =32V , V_{GS} =0V , T_{J} =25°C			1	uA
I _{GSS}	Gate-Source Leakage Current	V_{GS} =±20V , V_{DS} =0V			±100	nA

On Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =10V , I _D =20A			1.8	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_D=250uA$	1.0		2.5	V

Dynamic and switching Characteristics (NOTE 4)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Q_g	Total Gate Charge			166		
Q_gs	Gate-Source Charge	V_{DS} =32V , V_{GS} =10V , I_{D} =40A		30		nC
Q_{gd}	Gate-Drain Charge			68		
$T_{d(on)}$	Turn-On Delay Time	V_{DS} =20V , V_{GS} =10V , R_{G} =1 Ω , I_{D} =40A		22		
T _r	Rise Time			75		nS
$T_{d(off)}$	Turn-Off Delay Time			60		110
T_f	Fall Time			36		
C _{iss}	Input Capacitance	V _{DS} =25V , V _{GS} =0V , F=1MHz		7850		
C _{oss}	Output Capacitance			1730		pF
C _{rss}	Reverse Transfer Capacitance			500		
R_g	Gate resistance	V _{GS} =0V , V _{DS} =0V , F=1MHz		2.4		Ω

Drain-Source Diode Characteristics and Ratings

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current	V _G =V _D =0V, Force Current			195	Α
V_{SD}	Diode Forward Voltage	V _{GS} =0V , I _S =1A , T _J =25°C			1.2	V

NOTES:

- 1. Repetitive Rating: Pulsed width limited by maximum junction temperature.
- 2. The EAS data shows Max. rating. The test condition is V_{DD} =25V, L=1mH, R_G =25 Ω .
- 3. The data tested by pulsed , pulse width \leqq 300us , duty cycle \leqq 2%.
- 4. Guaranteed by design, not subject to production testing.





Characteristics Curves

FIG.1-Typical Output Characteristics

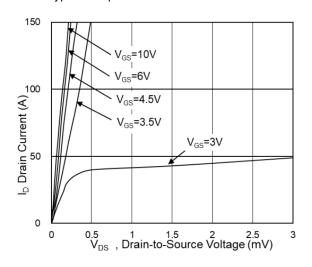


FIG.2-On-Resistance vs. G-S Voltage

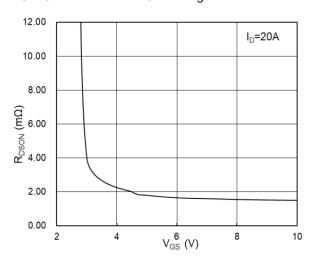


FIG.3-Source Drain Forward Characteristics

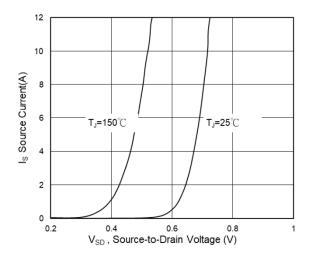


FIG.4-Gate Charge Characteristics

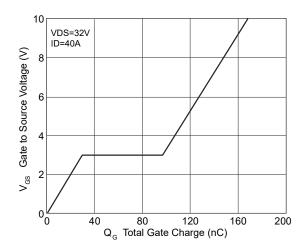


FIG.5-Normalized $V_{\text{GS(th)}}$ vs. T_{J}

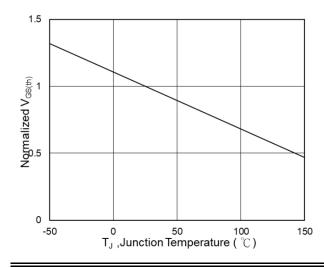
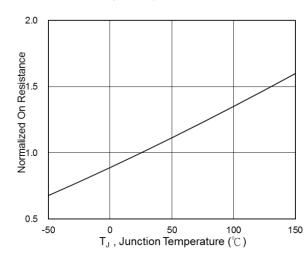


FIG.6-Normalized R_{DSON} vs. T_{J}

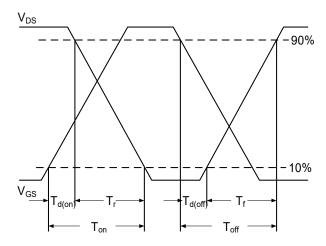




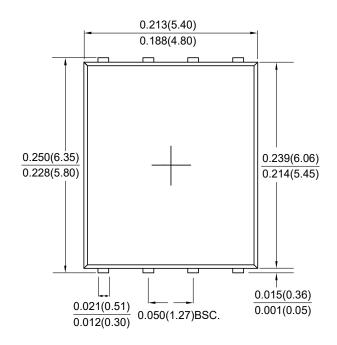


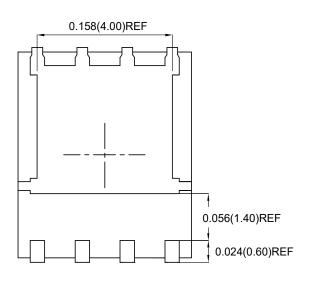
Characteristics Curves

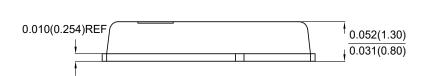
FIG.7-Switching Time Waveform

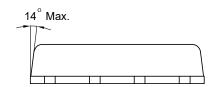


Package Outline Dimensions









PPAK5X6

Dimensions in inches and (millimeters)





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